



**RF360**  
**Europe GmbH**

## **Data sheet**

**SAW comb filter**  
Automotive telematics  
GNSS L1; GNSS L2L5

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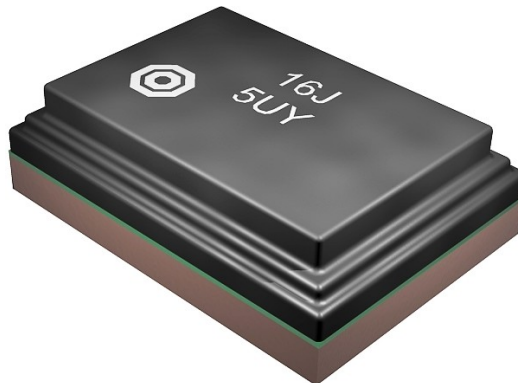
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## 1 Application

- Low-loss, pre-LNA comb filter for GNSS
- Low group delay ripple
- Usable pass band 65 MHz (L1)
- Usable pass band 88 MHz (L2L5)

## 2 Features

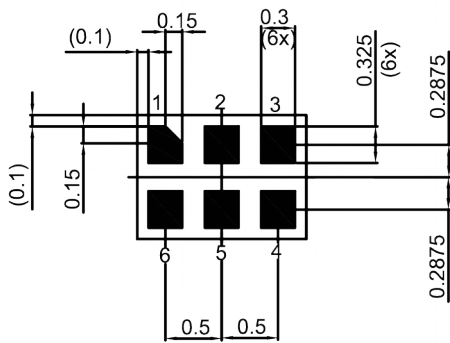
- Package size  $1.5_{\pm 0.1}$  mm  $\times$   $1.1_{\pm 0.1}$  mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family  
(Grade 2:  $-40$  °C to  $+105$  °C)



**Figure 1:** Picture of component with example of product marking.

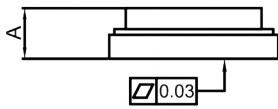
### 3 Package

BOTTOM VIEW

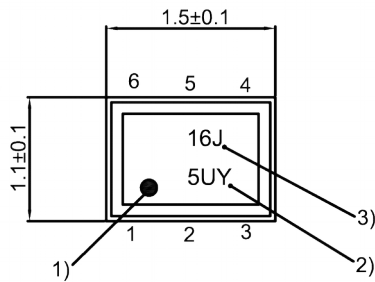


Pad and pitch tolerance  $\pm 0.05$

SIDE VIEW

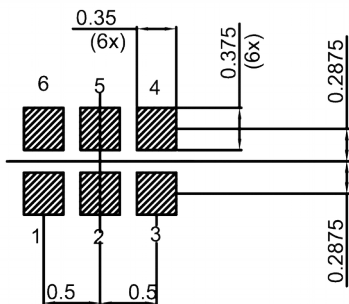


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern  
THRU VIEW



Landing pad tolerance  $-0.02$

**Figure 2:** Drawing of package with package height  $A = 0.45$  mm (max.). See Sec. Package information (p. 19).

### 4 Pin configuration

- 2 Input
- 5 Output
- 1, 3, 4, 6 Ground

5 Matching circuit

■  $L_{p2} = 3.9 \text{ nH}$

■  $L_{p5} = 5.3 \text{ nH}$

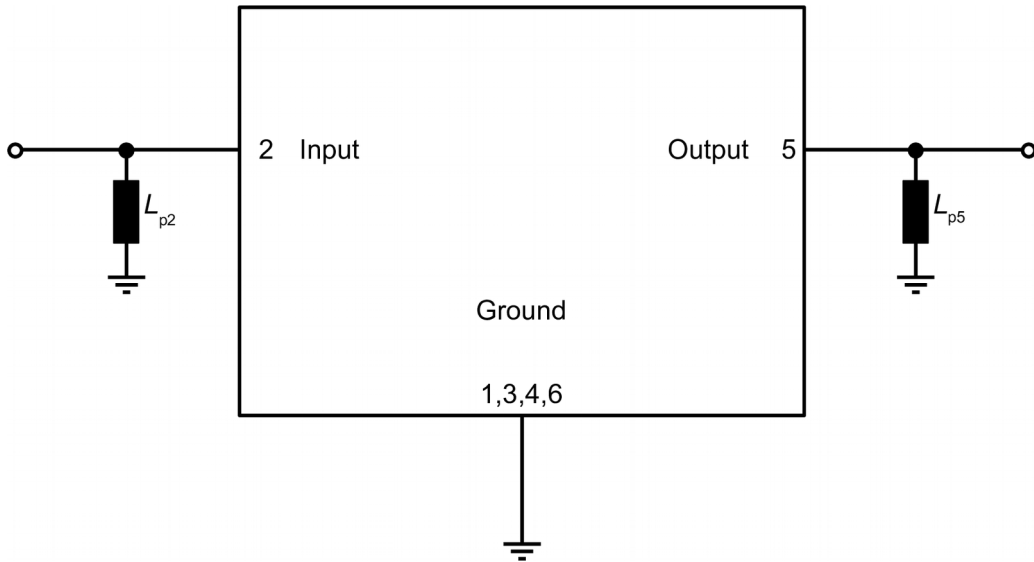


Figure 3: Schematic of matching circuit.

## 6 Characteristics

Temperature range for specification	$T_{SPEC}$	= -40 °C ... +105 °C
Input terminating impedance	$Z_{IN}$	= 50 $\Omega$ // 3.9 nH <sup>1)</sup>
Output terminating impedance	$Z_{OUT}$	= 50 $\Omega$ // 5.3 nH <sup>1)</sup>

Characteristics				min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Pass band 1</b>							
<b>Center frequency</b>			$f_C$	—	1210	—	MHz
<b>Maximum insertion attenuation</b>			$\alpha_{max 1}$				
	1166... 1186	MHz		—	1.1	1.6	dB
	1197... 1217	MHz		—	0.9	1.3	dB
	1217... 1237	MHz		—	1.0	1.4	dB
	1237... 1254	MHz		—	1.1	1.5	dB
<b>Amplitude ripple (p-p)</b>			$\Delta\alpha_1$				
	1166... 1186	MHz		—	0.4	0.9	dB
	1197... 1217	MHz		—	0.15	0.5	dB
	1217... 1237	MHz		—	0.3	0.6	dB
	1237... 1254	MHz		—	0.2	0.7	dB
<b>Group delay ripple</b>			$\Delta\tau_{var 1}$				
	1166... 1186	MHz		—	3	6	ns <sup>2)</sup>
	1197... 1217	MHz		—	2	5	ns <sup>2)</sup>
	1217... 1237	MHz		—	3	7	ns <sup>2)</sup>
	1237... 1254	MHz		—	6	9	ns <sup>2)</sup>
<b>Maximum VSWR</b>			$VSWR_{max 1}$				
@ input port	1166... 1254	MHz		—	1.5	1.9	
@ output port	1166... 1254	MHz		—	1.5	1.9	
<b>Pass band 2</b>							
<b>Center frequency</b>			$f_C$	—	1577.5	—	MHz
<b>Maximum insertion attenuation</b>			$\alpha_{max 2}$				
	1545... 1560	MHz		—	1.8	2.2	dB
	1557... 1563	MHz		—	1.8	2.2	dB
	1565... 1585	MHz		—	2.0	2.6	dB
	1593... 1610	MHz		—	1.9	2.5	dB
<b>Amplitude ripple (p-p)</b>			$\Delta\alpha_2$				
	1545... 1560	MHz		—	0.1	0.7	dB
	1557... 1563	MHz		—	0.1	0.5	dB
	1565... 1585	MHz		—	0.2	0.7	dB
	1593... 1610	MHz		—	0.3	0.7	dB
<b>Group delay ripple</b>			$\Delta\tau_{var 2}$				
	1545... 1560	MHz		—	2	5	ns <sup>2)</sup>
	1557... 1563	MHz		—	1	5	ns <sup>2)</sup>

Characteristics			min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
	1565... 1585	MHz	—	5	8	ns <sup>2)</sup>
	1593... 1610	MHz	—	4	8	ns <sup>2)</sup>
<b>Maximum VSWR</b>						
						VSWR <sub>max 2</sub>
@ input port	1545... 1610	MHz	—	1.5	1.9	
@ output port	1545... 1610	MHz	—	1.5	1.9	
<b>Minimum attenuation</b>						
						$\alpha_{min}$
	100... 894	MHz	26	29	—	dB
	894... 915	MHz	25	28	—	dB
	925... 960	MHz	24	26	—	dB
	960... 1000	MHz	23	25	—	dB
	1000... 1090	MHz	21	25	—	dB
	1090... 1125	MHz	25	29	—	dB
	1125... 1135	MHz	10	20	—	dB
	1300... 1447.9	MHz	25	28	—	dB
	1447.9... 1462.9	MHz	28	31	—	dB
	1463... 1496	MHz	14 <sup>3)</sup>	26	—	dB
	1463... 1496	MHz	10	26	—	dB
	1660... 1710	MHz	23	26	—	dB
	1710... 1785	MHz	23	27	—	dB
	1785... 1980	MHz	22	25	—	dB
	1980... 2180	MHz	22	25	—	dB
	2180... 2400	MHz	25	27	—	dB
	2400... 2700	MHz	27	30	—	dB
	2700... 3120	MHz	32	35	—	dB
	3120... 3400	MHz	26	31	—	dB
	3400... 3800	MHz	36	40	—	dB
	3800... 4000	MHz	32	36	—	dB
	4000... 6000	MHz	25	30	—	dB

- 1) See Sec. Matching circuit (p. 6).  
 2) Measured with an aperture of 1 MHz.  
 3) Valid for typical temperature  $T = +25$  °C.



## 7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +105\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +105\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
Input power	$P_{IN}$	
@ input port: 1166 ... 1254 MHz	15 dBm	Continuous wave for 5000 h @ 50 °C.
@ input port: 1545 ... 1610 MHz	15 dBm	Continuous wave for 5000 h @ 50 °C.

<sup>1)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficient

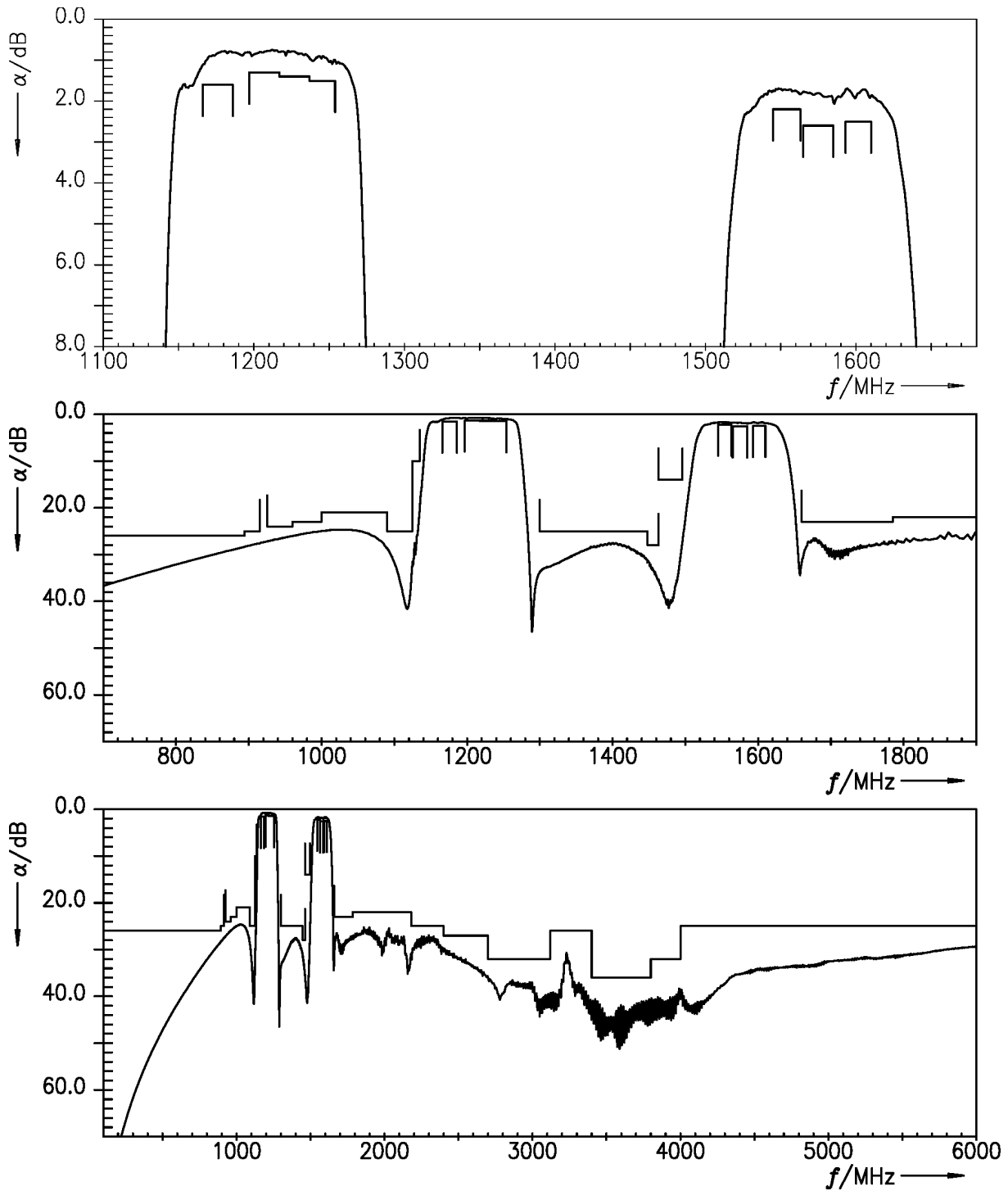


Figure 4: Attenuation.

9 Reflection coefficients

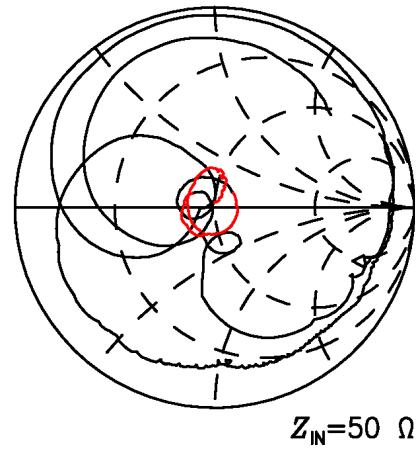
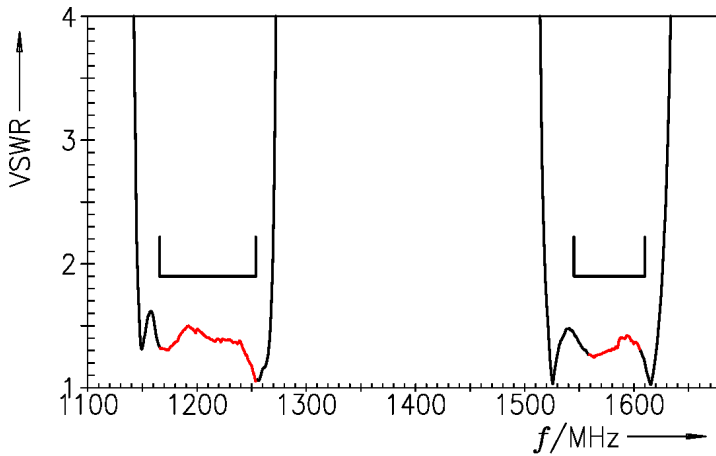


Figure 5: Reflection coefficient at input port.

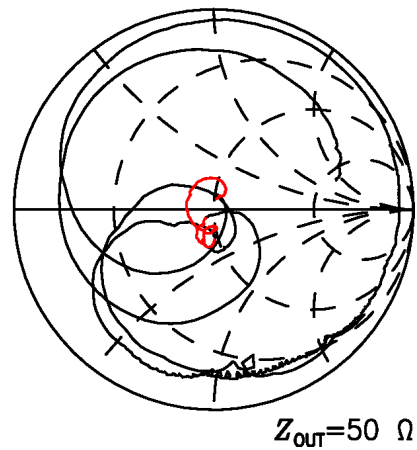
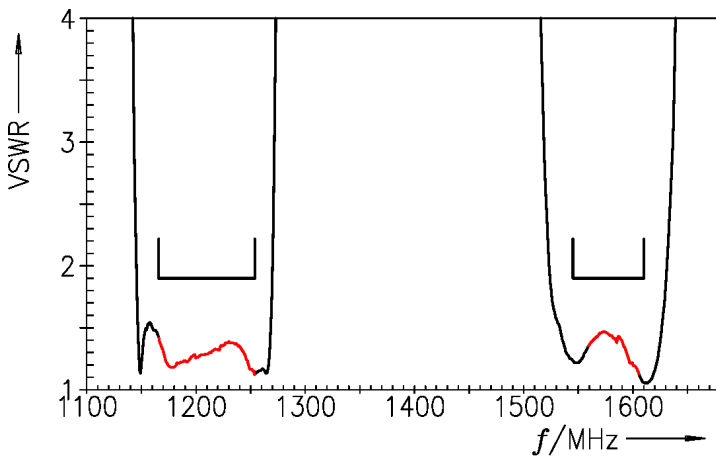


Figure 6: Reflection coefficient at output port.

10 Group delay

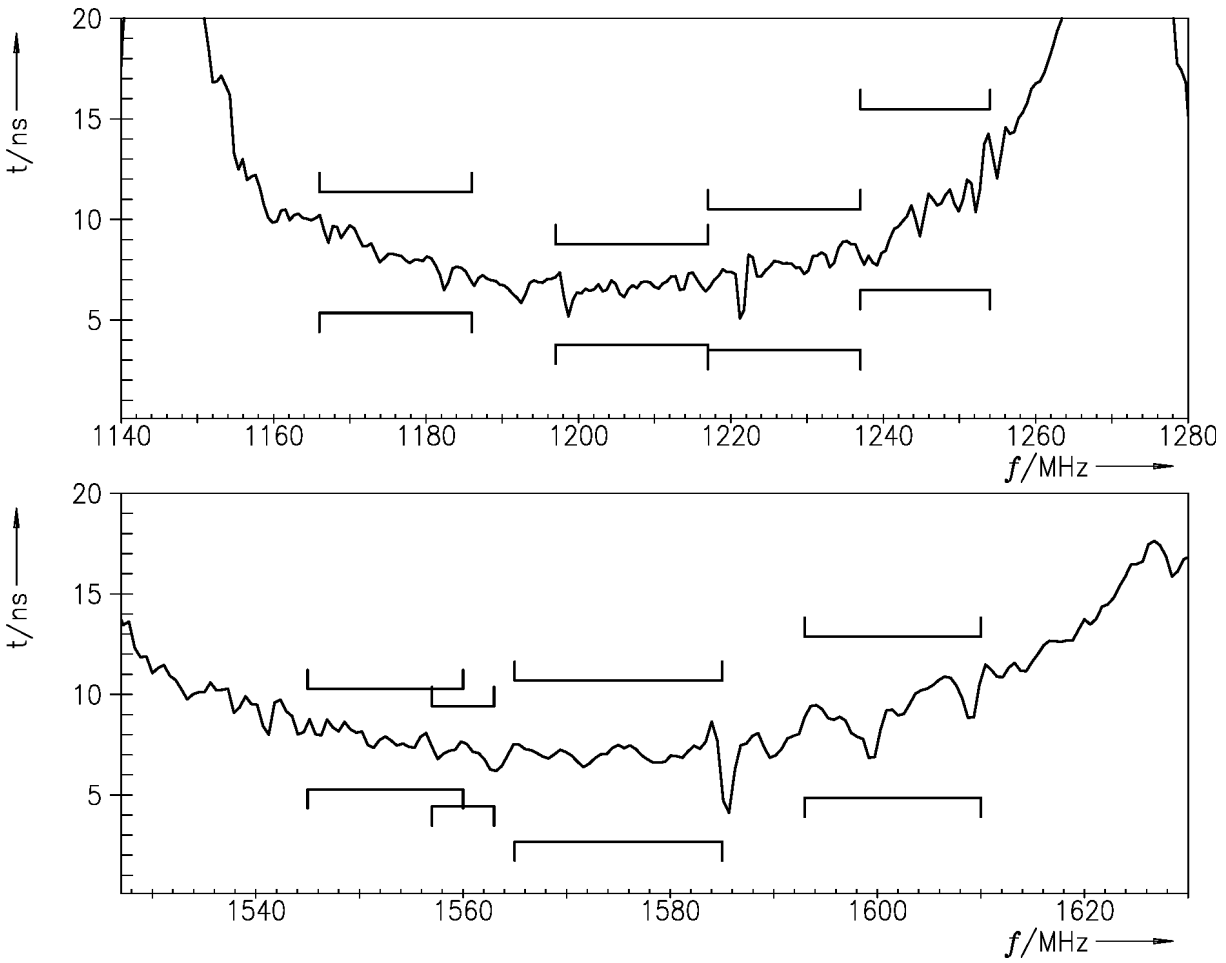
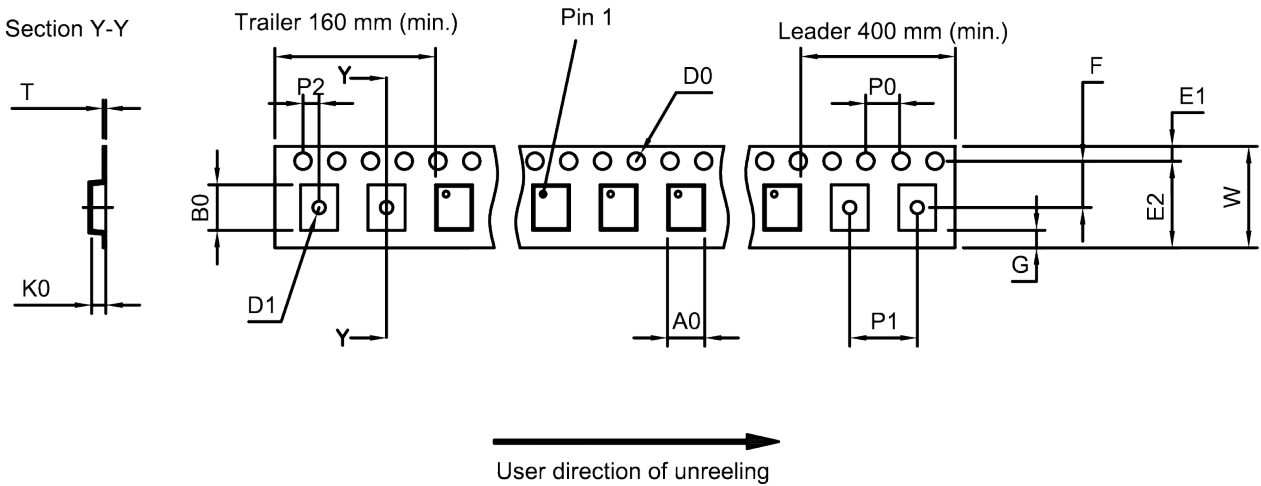


Figure 7: Group delay ripple.

11 Packing material

11.1 Tape



**Figure 8:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	1.27±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	4.0±0.1 mm
B <sub>0</sub>	1.67±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D <sub>1</sub>	0.5+0.1/-0 mm	K <sub>0</sub>	0.55±0.05 mm	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0±0.1 mm		

**Table 1:** Tape dimensions.

11.2 Reel with diameter of 180 mm

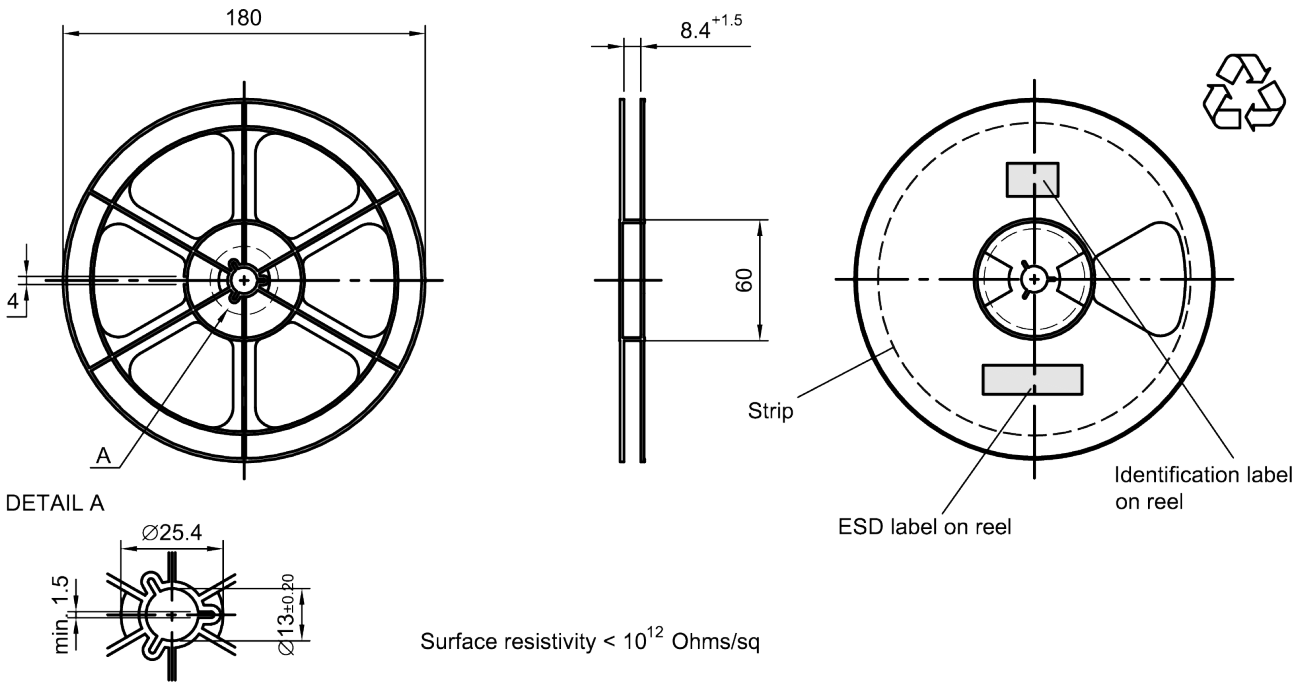


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

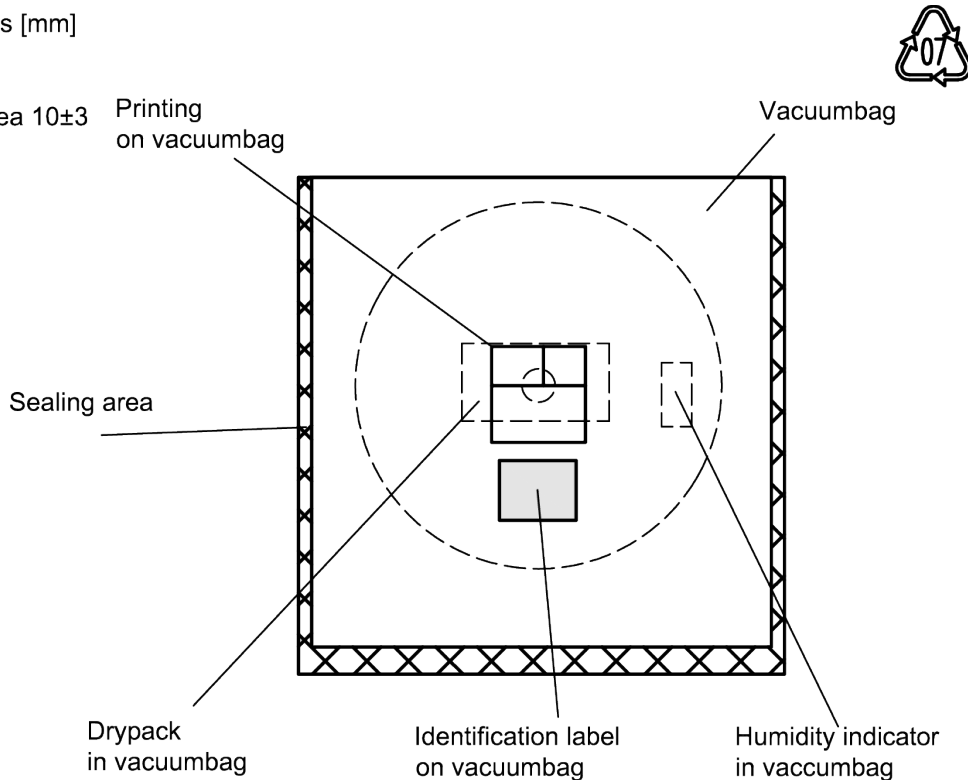


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

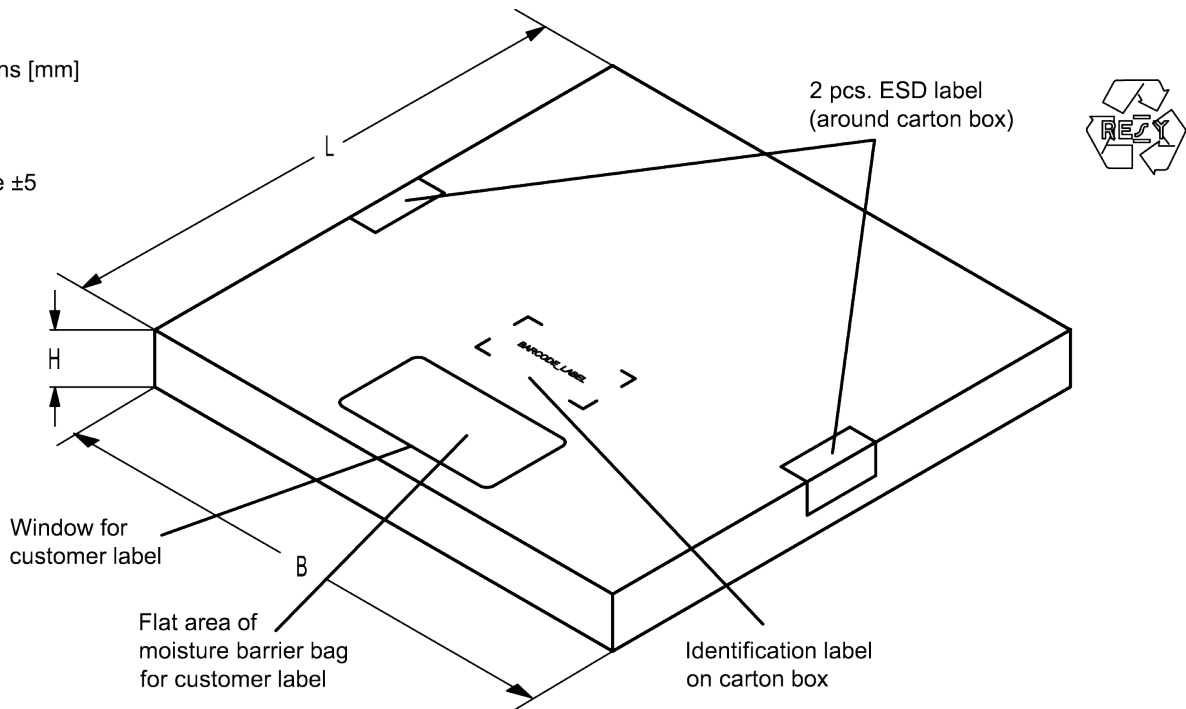
Dimensions [mm]

L = 188

B = 188

H = 30

Tolerance  $\pm 5$



**Figure 11:** Drawing of folding box for reel with diameter of 180 mm.

**12 Marking**

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.  
**16J** => **1234**  
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$  **1234**

The BASE32 code for product type B2651 is 2JV.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.  
**5UY** => **12345**  
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

**Table 2:** Lists for encoding and decoding of marking.

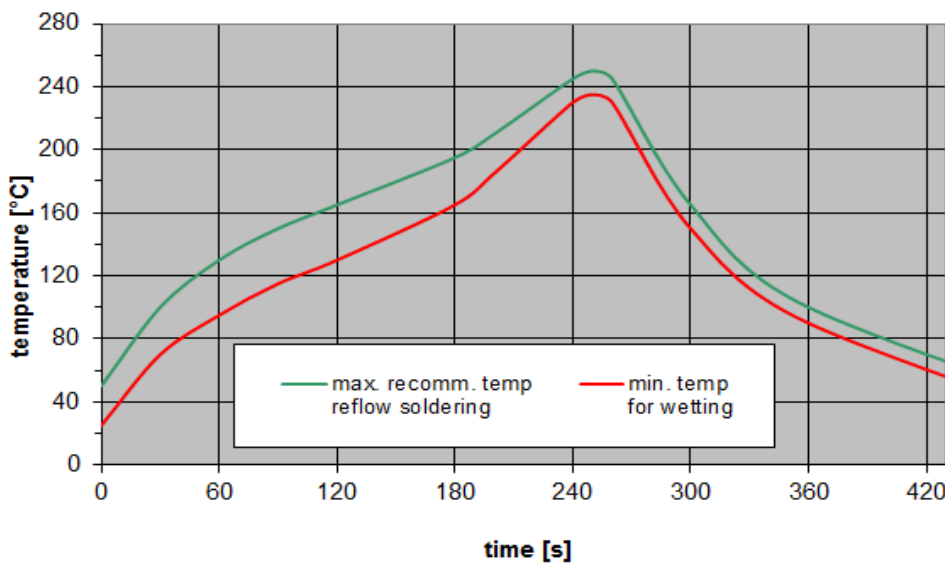


### 13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 12:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

## 14 Annotations

### 14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 15 Cautions and warnings

### 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

### 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 15.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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